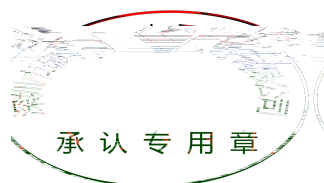
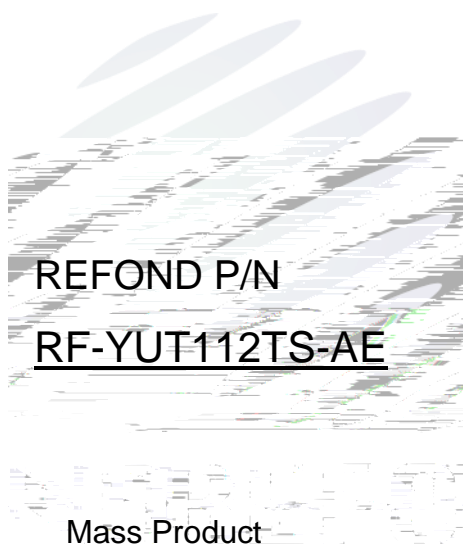
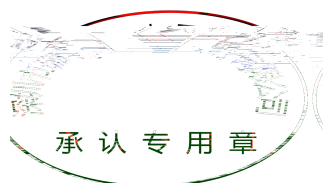
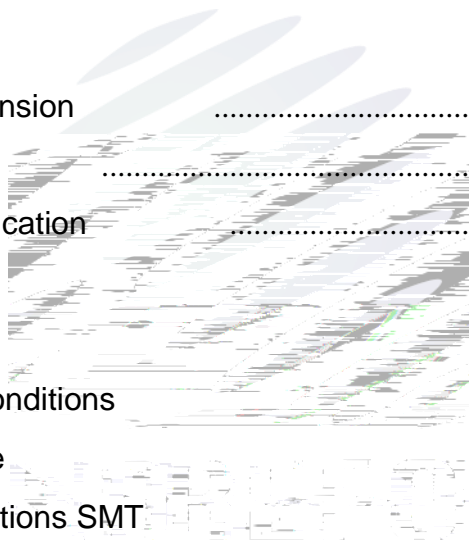


# SPECIFICATION



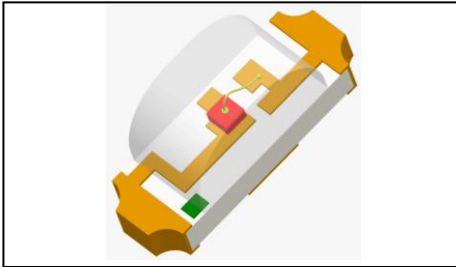
# Contents

- 1. Description
  - 1.1 General Description
  - 1.2 Features
  - 1.3 Application
  - 1.4 Package Dimension
  - 1.5 Product Parameters
  - 1.6 Typical Optical Characteristics Curves
- 2. Packaging
  - 2.1 Packaging Specification
    - 2.1.1 Carrier Tape Dimension ..... 11
    - 2.1.2 Reel Dimension ..... 11
    - 2.1.3 Label Form Specification ..... 12
  - 2.2 Moisture Resistant Packing
  - 2.3 Cardboard Box
  - 2.4 Reliability Test Items And Conditions
  - 2.5 Criteria For Judging Damage
- 3. SMT Reflow Soldering Instructions SMT
  - 3.1 SMT Reflow Soldering Instructions SMT
- 4. Handling Precautions
  - 4.1 Handling Precautions



## 1. Description

### 1.1 General Description



The Colour LED which was fabricated using a yellow chip Package Dimension :  
3.2mmX1.0mmX1.5mm.

LED

3.2mmX1.0mmX1.5mm

### 1.2 Features

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Moisture sensitivity level: Level 3.

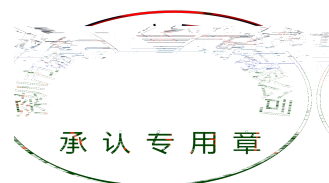
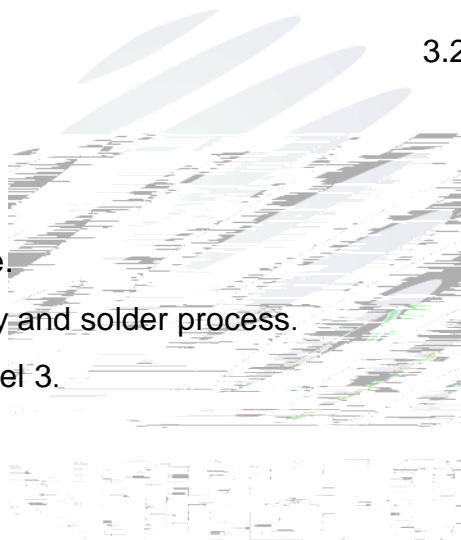
RoHS compliant.

### 1.3 Application

Optical indicator.

Switch and symbol, display.

General use.



## 1.4 Package Dimension

Fig.1-1 Top view

Fig.1-2 Side view

Fig.1-3 Bottom view

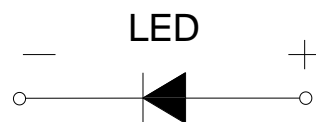


Fig.1-4 Polarity

Fig.1-5 Soldering patterns

### Notes

All dimensions units are millimeters.

All dimensions tolerances are  $\pm$

## 1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Test Condition	Symbol		Value			Unit
				Min. ( )	Typ.	Max.	
Spectral Half Bandwidth	I <sub>F</sub> =20mA	Δ		--	15	--	nm
Forward Voltage	I <sub>F</sub> =20mA	V <sub>F</sub>	1L	1.8	--	2.4	V
Dominant Wavelength	I <sub>F</sub> =20mA	λ <sub>D</sub>	2K	585	--	590	nm
			2L	590	--	595	nm
Luminous Intensity	I <sub>F</sub> =20mA	I <sub>v</sub>	1AP	90	--	120	mcd
			G20	120	--	150	mcd
			1AW	150	--	200	mcd
Viewing Angle	I <sub>F</sub> =20mA	θ		--	140	--	deg
Reverse Current	V <sub>R</sub> =5V	I <sub>R</sub>		--	--	10	μA
Thermal Resistance.	I <sub>F</sub> =20mA	R <sub>THJ-S</sub>		--	--	450	/W

Notes : V<sub>R</sub>=5V For test conditions. V<sub>R</sub>=5V

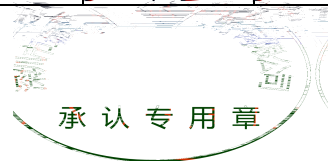
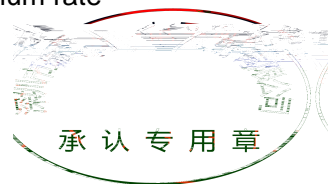


Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	$P_d$	48	mW
Forward Current	$I_F$	20	mA
Peak Forward Current Of Pulse	$I_{FP}$	60	mA
Electrostatic Discharge (HBM)	$E_{SD}$	2000	V
Operating Temperature	$T_{opr}$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	°C
Junction Temperature	$T_j$	95	°C

Notes

- 1/10 Duty cycle, 0.1ms pulse width.
- The above forward voltage measurement allowance tolerance is  $\pm 0.1V$ .
- The above dominant wavelength measurement allowance tolerance is  $\pm 2nm$ .
- The above luminous intensity measurement allowance tolerance  $\pm 10\%$ .
- Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
- All measurements were made under the standardized environment of Refond.
- When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate



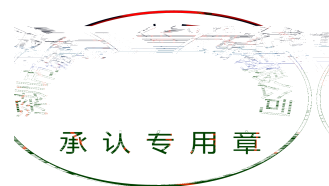
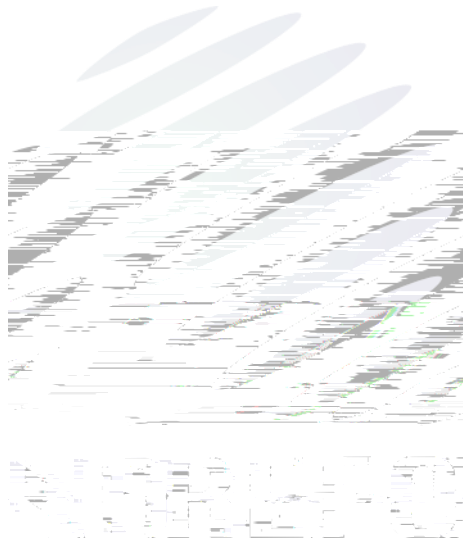
## cal Characteristics Curves

ig 1

-

F

Fig 1-6



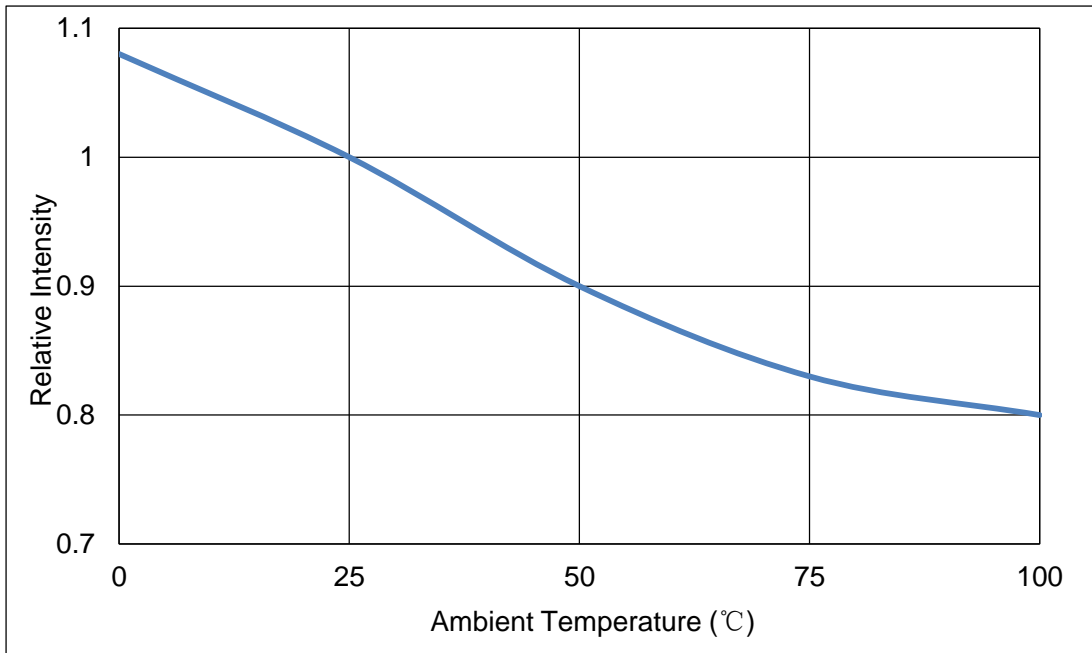


Fig 1-8 Pin Temperature Vs Relative Intensity

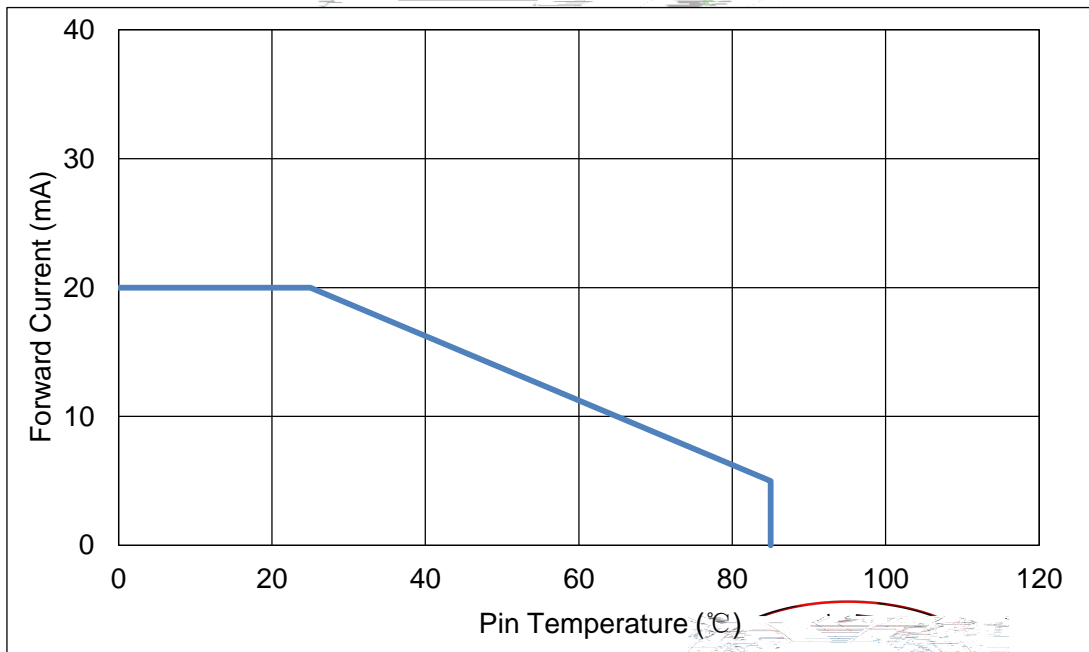
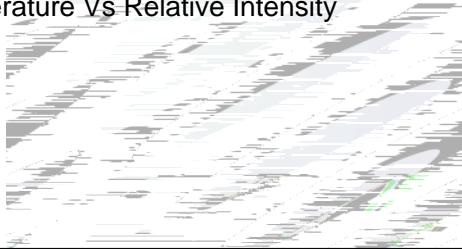
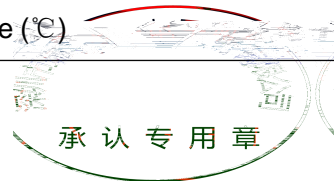


Fig 1-9 Pin Temperature Vs Forward Current



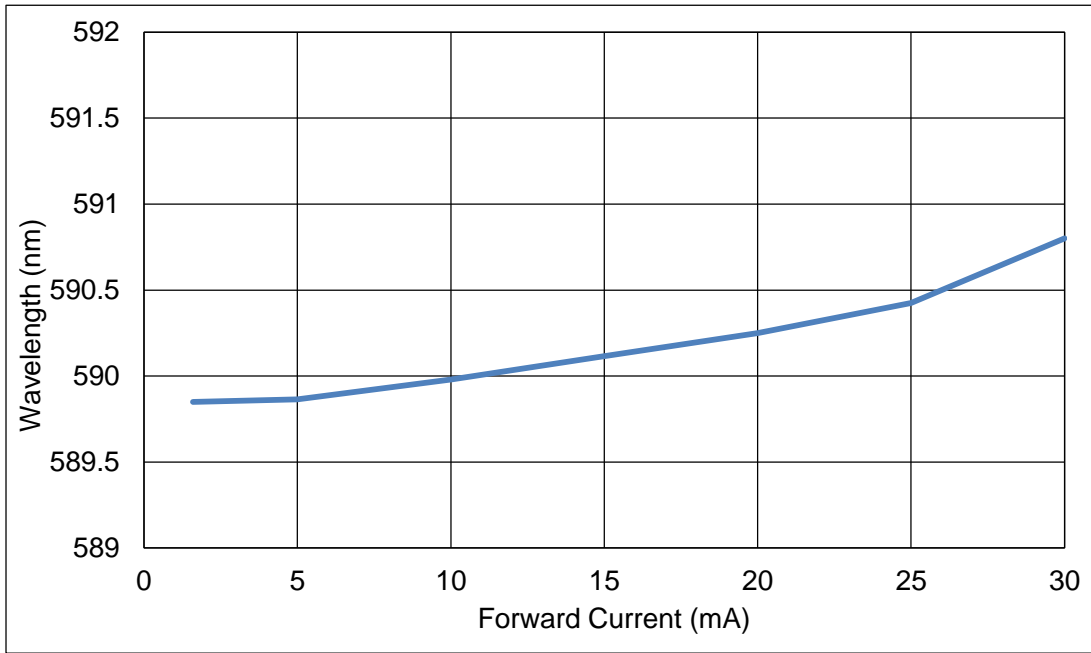


Fig 1-10 Forward Current Vs Dominate Wavelength (Ta=25°C)

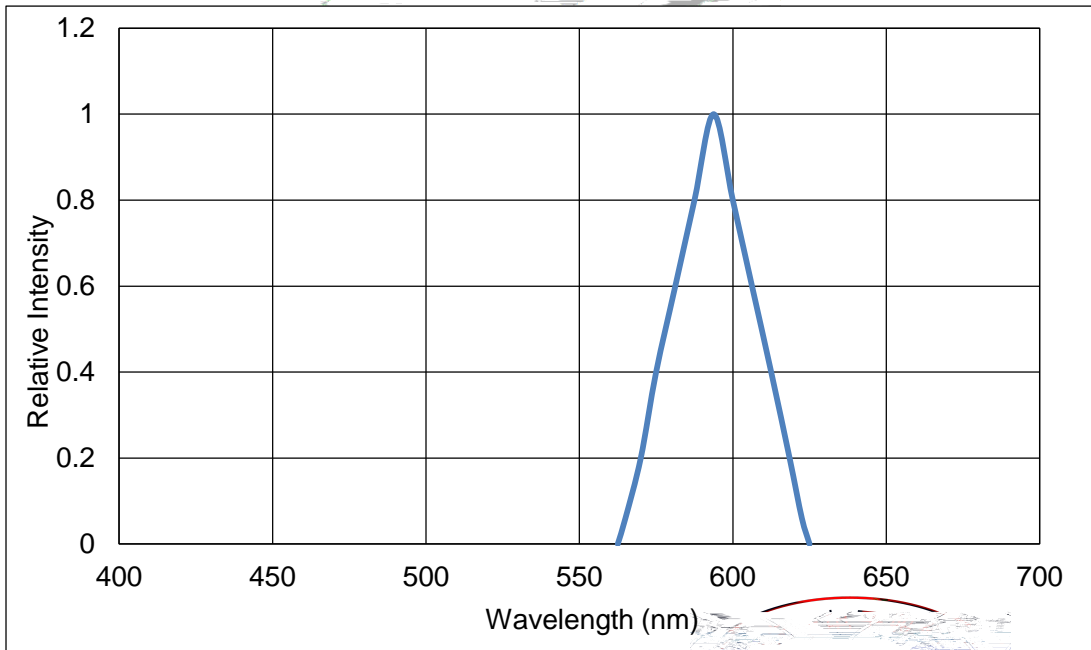
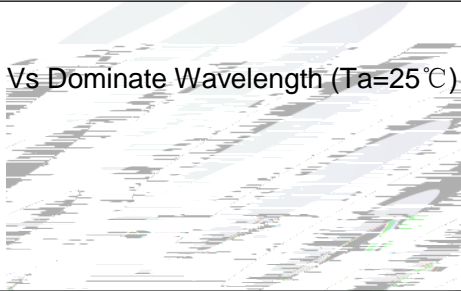
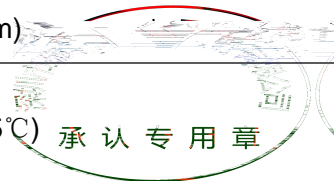


Fig 1-11 Relative Intensity Vs Wavelength (Ta=25°C)



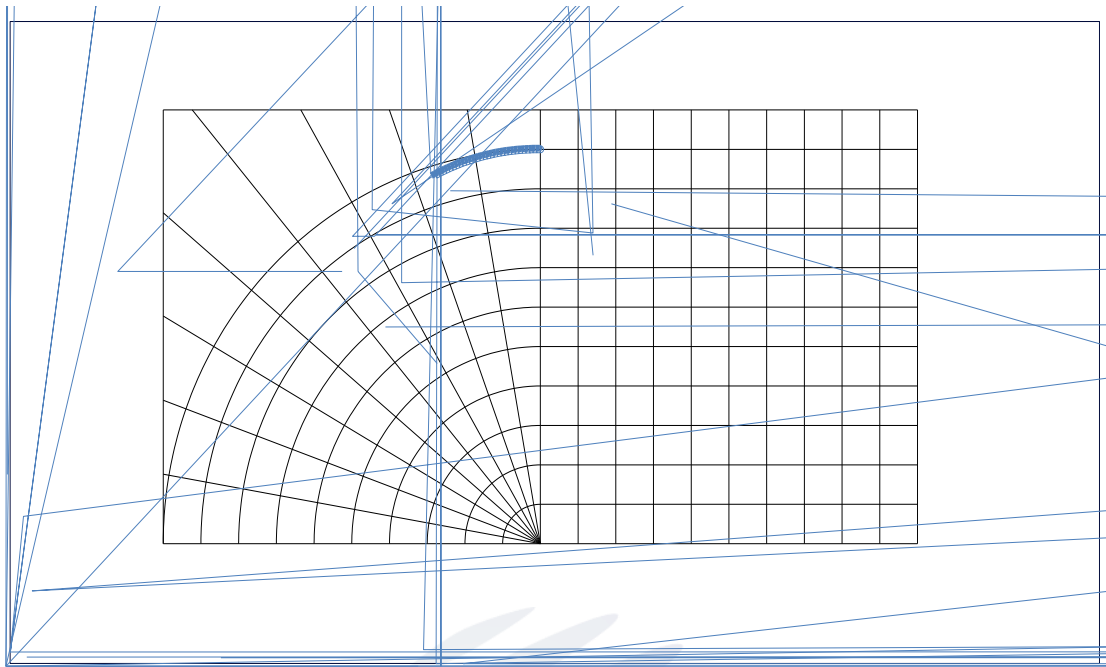
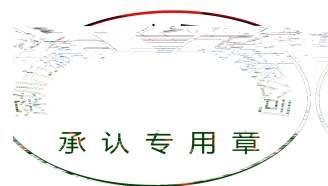
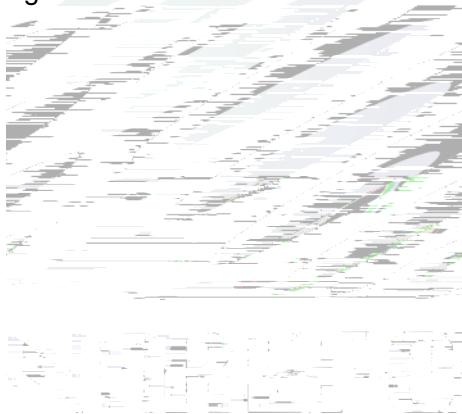
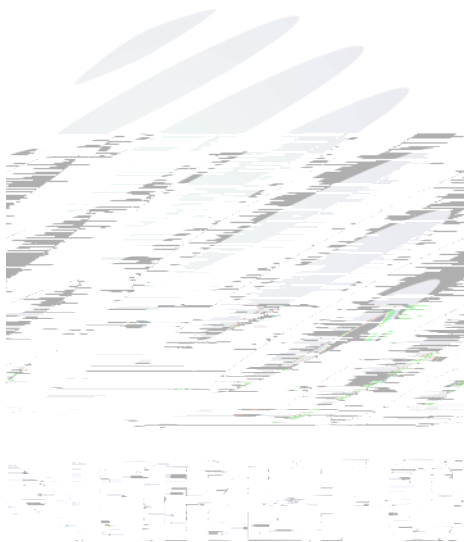


Fig 1-12 Diagram characteristics of radiation





### 2.1.3 Label Form Specification

Table 2-2 Parameter

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V <sub>F</sub>	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

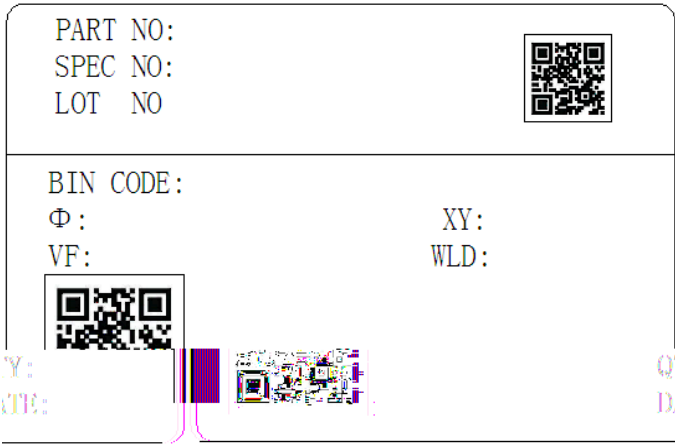


Fig. 2-3 Label Form Specification

### 2.2 Moisture Resistant Packing

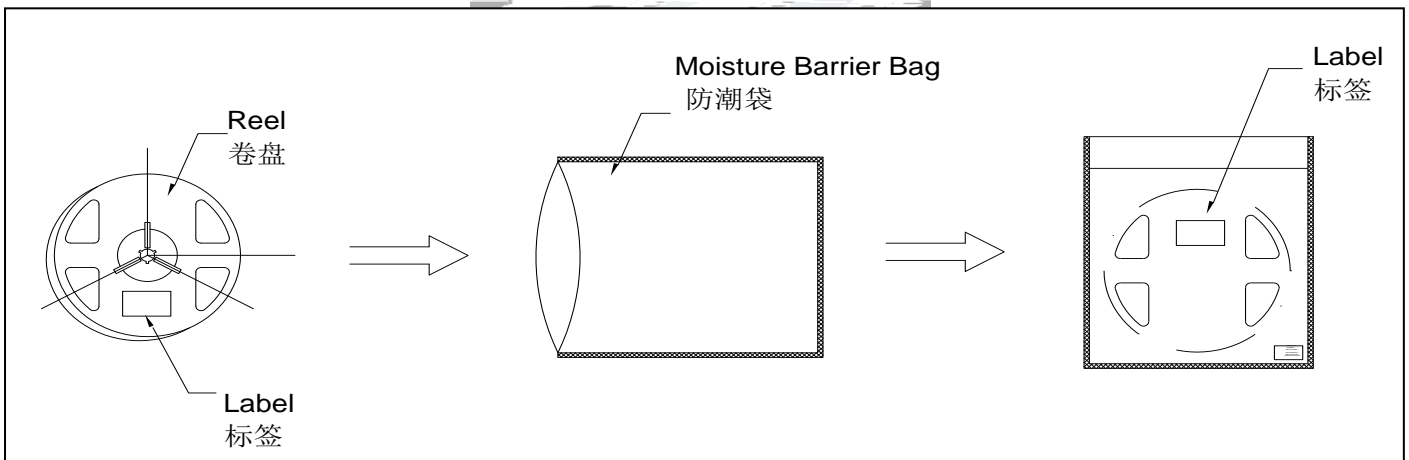
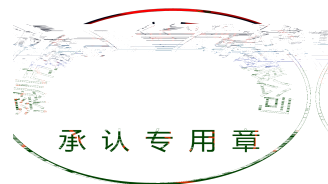
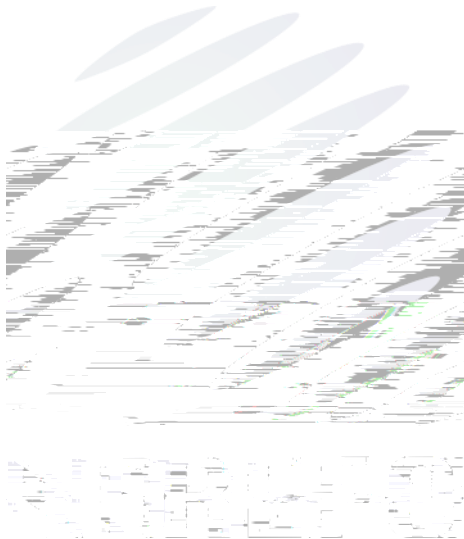


Fig.2-4 Moisture Resistant Packing





## 2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	$V_F$	$I_F=20mA$	-	U.S.L*)x1.1
Reverse Current	$I_R$	$V_R= 5V$	-	U.S.L*)x2.0
Luminous Flux		$I_F=20mA$	L.S.L*)x0.7	-

### Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

2.The above

### 3. SMT Reflow Soldering Instructions SMT 回流焊说明

#### 3.1 SMT Reflow Soldering Instructions SMT

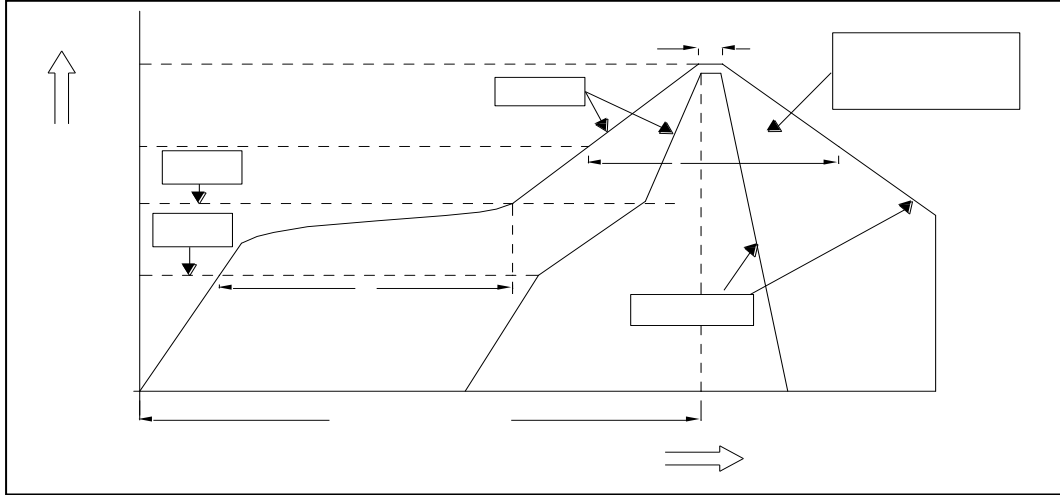


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameters

Average temperature rise speed	$T_{smax}$ $T_P$	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	( $T_{smin}$ )	150 °C
Preheating: Max temperature	( $T_{smax}$ )	200 °C
Preheating: Time	$T_{smin}$ $T_{smax}$	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature ( $T_L$ )		217 °C
Time limited to maintain high temperature: The Time ( $t_L$ )		60 Max 60s
Peak /Classification of temperature: / ( $T_P$ )		260 °C
Time limit classification of peak temperature time $t_p$		10 Max 10s
( $T_P$ ) 5 °C Hold time within 5		30 Max 30s
C with the actual peak temperature (TP)		
Cooling speed		6 °C/ Max 6 °C/ s
25 °C	Needed time from 25 °C to $T_p$	8 Max 8 minutes

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings, LED will be damaged.

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

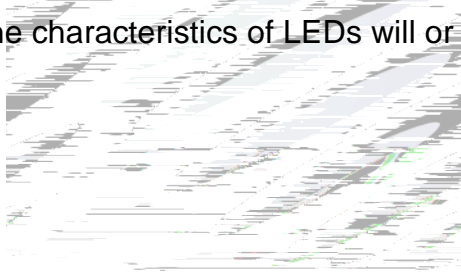
(1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds.

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED



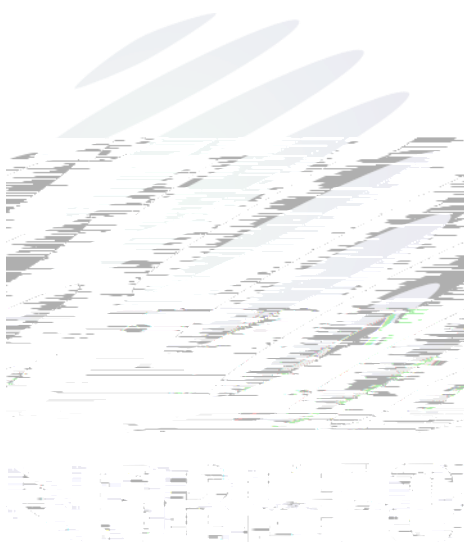
3.1.3 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.





(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

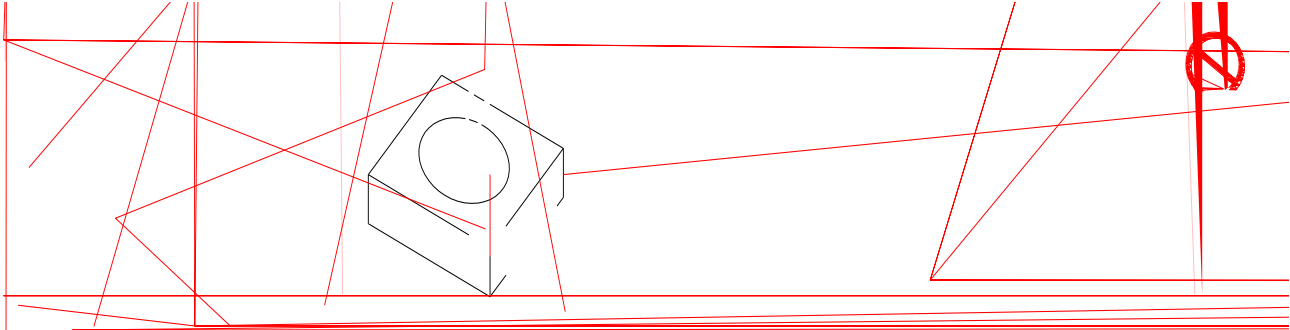
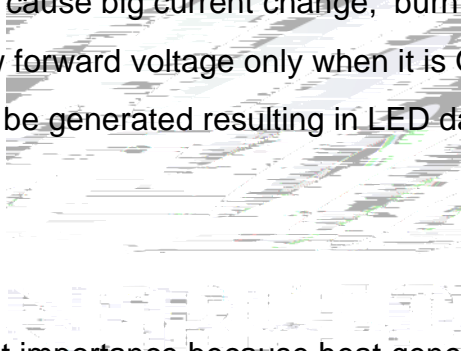


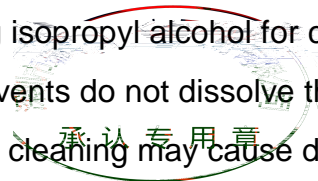
Fig 4-1 产品使用注意事项

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.



(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the



LED.

Table 4-1 Storage

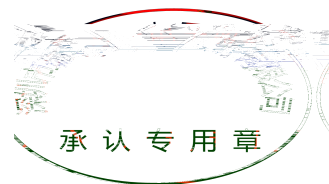
Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60 ± 5		24hours 24

(8) If the moisture absorbent material ( silica gel ) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition ( 65±5 ) °C for above 24 hours.

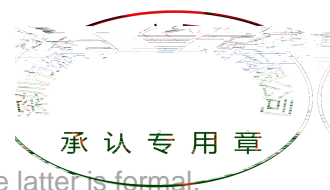
If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) Other points for attention, please refer to our relevant information.







Declare

This specification is written both in English and in Chinese and the latter is formal.